



GSX11N70E

MOSFET

Metal Oxide Semiconductor Field Effect Transistor

Super Junction MOSFET

700V Super Junction Power Transistor

GSX11N70E

Data Sheet

Ver 1.0

2019-3-20

700V 11A Power MOSFET

■ Description

Group Semiconductor (GS) has series Multi-EPI Super-Junction power MOSFET platforms for voltage up 500V to 1000 volts, both with design service and manufacturing capability, including cell, termination design and simulation.

The GS 700V 11A Power MOSFET is a Low voltage N channel Multi-EPI Super-Junction power MOSFET sample with advanced technology to have better characteristics, such as fast switching time, low C_{iss} and C_{rss}, low on resistance and excellent avalanche characteristics, making it especially suitable for applications which require superior power density and outstanding efficiency.



■ Features

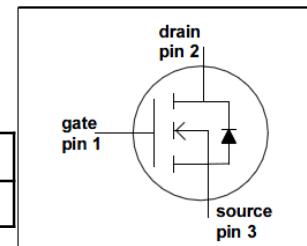
RDS(ON)=0.45Ω @VGS = 10V

VDS = 700V

ID (@ VGS=10V) = 6.5A

■ PKG

GSA11N70E	GSP11N70E	GSB11N70E	GSD11N70E	GSD11N70E
TO-220Fullpak	TO-220	TO-263	TO-252	TO-251



■ Absolute Maximum Ratings (TC = 25° C, unless otherwise specified)

Symbol	Parameter	GSP11N70E	GSA11N70E	Unit
V _{DSS}	Drain-Source Voltage	700		V
I _D	Drain Current - Continuous (TC = 25°C) - Continuous (TC = 100°C)	11*	7*	A
I _{DM}	Drain Current - Pulsed (Note 1)	42		A
V _{GSS}	Gate-Source voltage	±30		V
E _A	Single Pulsed Avalanche Energy (Note 2)	260		mJ
I _{AR}	Avalanche Current (Note 1)	2		A
E _{AR}	Repetitive Avalanche Energy (Note 1)	1		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	15		V/ns
dVds/dt	Drain Source voltage slope (V _{ds} =480V)	50		V/ns
P _D	Power Dissipation (TC = 25°C)	151	35	W
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150		°C
T _L	Max. Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300		°C

700V 11A Power MOSFET

■ Thermal Characteristics

Symbol	Parameter	GSA11N70E	GSP11N70E	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	1.2	1.2	°C/W
R _{θCS}	Thermal Resistance, Case-to-Sink Typ.	0.5	0.5	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	62	62	°C/W

Symbol	Parameter	Value (TO220)	Unit
R _{θJA} ⁽⁶⁾	Maximum Junction-to-Ambient	82	°C/W
R _{θCS} ⁽⁶⁾	Maximum Case-to-sink	0.6	°C/W
R _{θJC} ^{(7),(8)}	Maximum Junction-to-Case θ	4.1	°C/W

1. The power dissipation PD is based on TJ(MAX)=150° C in a TO251 package, using junction-to-case thermal resistance.
2. Repetitive rating, pulse width limited by junction temperature TJ(MAX)=150° C.
3. L=1mH, Starting TJ=25° C.
4. L = 10mH, starting TJ = 25° C.
5. L=60mH, starting TJ = 25° C.
6. The tests are performed with the device with T A =25° C.
7. The R □ JA is the sum of the thermal impedance from junction to case R □ JC and case to ambient.
8. These curves are based on the junction-to-case thermal impedance, assuming a maximum junction temperature of TJ(MAX)=150° C.

700V 11A Power MOSFET

■ Electrical Characteristics (TJ=25° C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250µA, T _J = 25°C	700	--	--	V
		V _{GS} = 0V, I _D = 250µA, T _J = 150°C	--	750	--	V
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250µA, Referenced to 25°C	--	0.6	--	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 700V, V _{GS} = 0V -T _J = 150°C	-- 10	-- -	1	µA µA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V	--	--	-100	nA
On Characteristics						
V _{G(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250µA	2.5	--	4.5	V
R _{D(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 5.5A	--	0.4	0.45	Ω
g _F S	Forward Transconductance	V _{DS} = 40V, I _D = 5.5A	--	16	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	--	720	-	pF
C _{oss}	Output Capacitance		--	20	-	pF
C _{rss}	Reverse Transfer Capacitance		--	1.5	--	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400V, I _D = 5.5A R _G = 20Ω (Note 4)	--	15	--	ns
t _r	Turn-On Rise Time		--	10	--	ns
t _{d(off)}	Turn-Off Delay Time		--	110	--	ns
t _f	Turn-Off Fall Time		--	9	--	ns
Q _g	Total Gate Charge	V _{DS} = 400V, I _D = 5.5A V _{GS} = 10V (Note 4)	--	32	--	nC
Q _{gs}	Gate-Source Charge		--	4	--	nC
Q _{gd}	Gate-Drain Charge		--	16	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current	--	--	9.2	A	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	30	A	
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 5.5A	--	0.9	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 5.5A dI/dt = 100A/µs	--	280	--	ns
Q _{rr}	Reverse Recovery Charge		--	3.3	--	µC

NOTES:

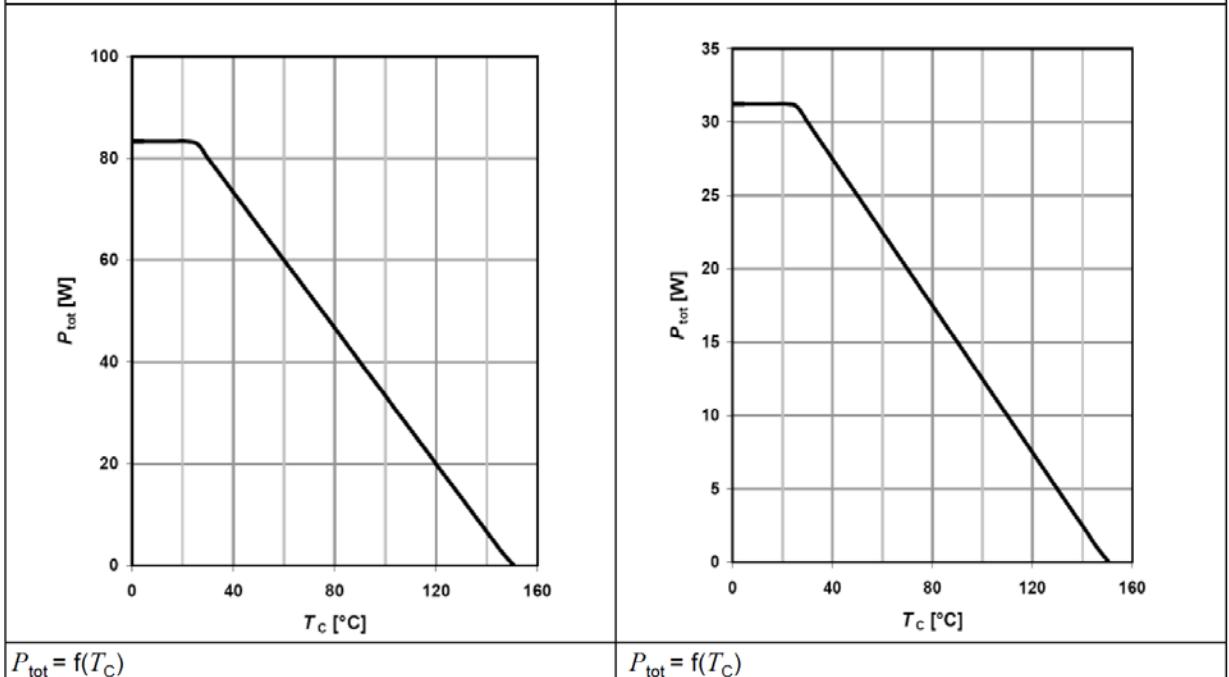
- Repetitive Rating: Pulse width limited by maximum junction temperature
- L=60mH, I_{AS}=3A, V_{DD}=150V, Starting T_J=25 °C
- I_{SD}<4.5A, dI/dt ≤ 200A/us, V_{DD} ≤ BV_{DSS}, Starting T_J = 25 °C
- Pulse Test: Pulse width ≤ 300us, Duty Cycle ≤ 2%
- Essentially Independent of Operating Temperature Typical Characteristics

700V 11A Power MOSFET

Typical Performance Characteristics

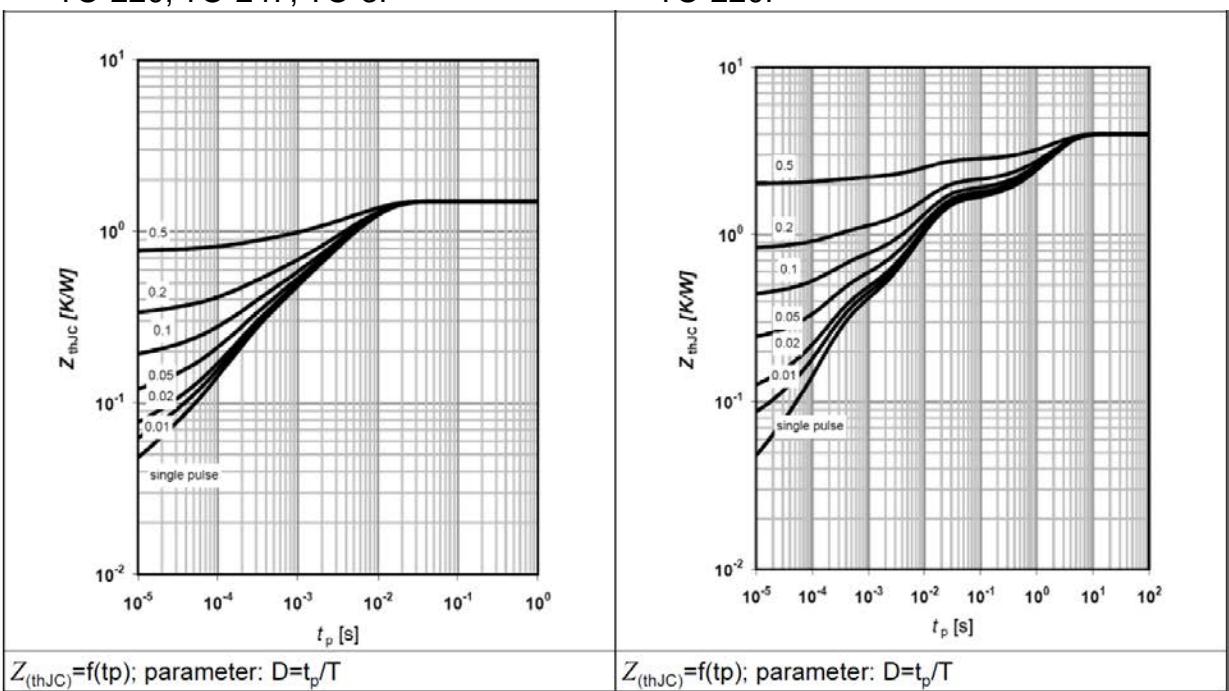
Power dissipation
TO-220, TO-247, TO-3P

Power dissipation
TO-220F



Max. transient thermal impedance
TO-220, TO-247, TO-3P

Max. transient thermal impedance
TO-220F

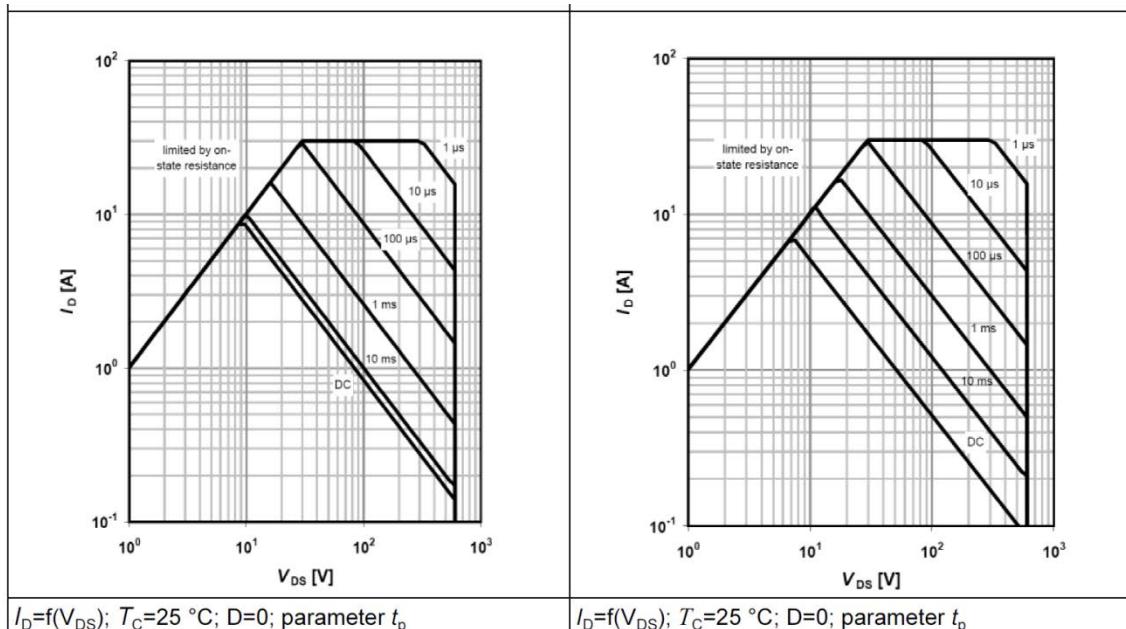


700V 11A Power MOSFET

Typical Performance Characteristics

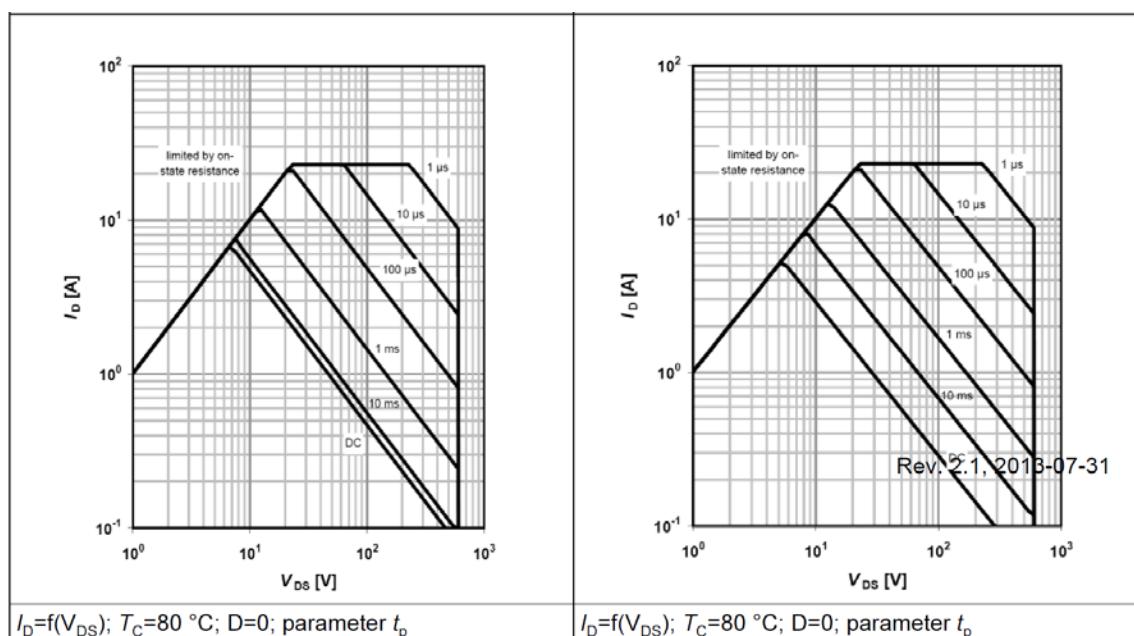
Safe operating area $T_C=25\text{ }^\circ\text{C}$
TO-220, TO-247, TO-3P

Safe operating area $T_C=25\text{ }^\circ\text{C}$
TO-220F



Safe operating area $T_C=80\text{ }^\circ\text{C}$
TO-220, TO-247, TO-3P

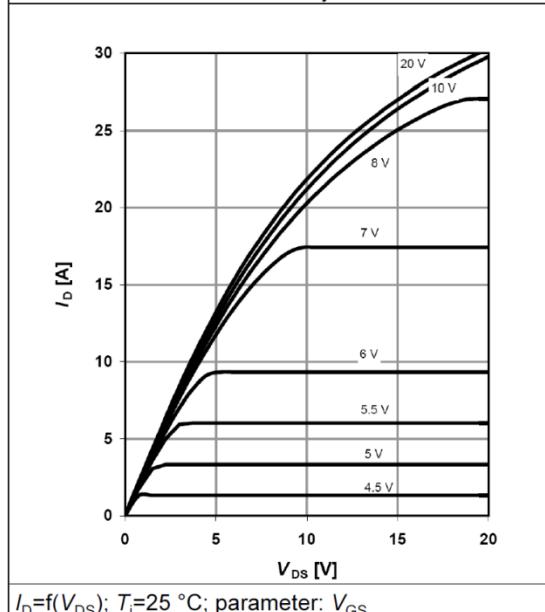
Safe operating area $T_C=80\text{ }^\circ\text{C}$
TO-220F



700V 11A Power MOSFET

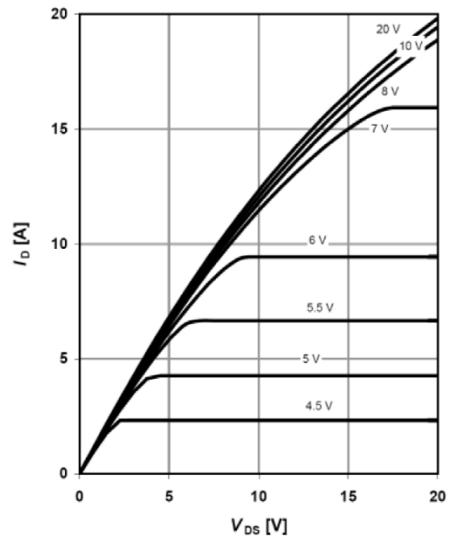
Typical Performance Characteristics

Typ. output characteristics $T_j=25\text{ }^\circ\text{C}$



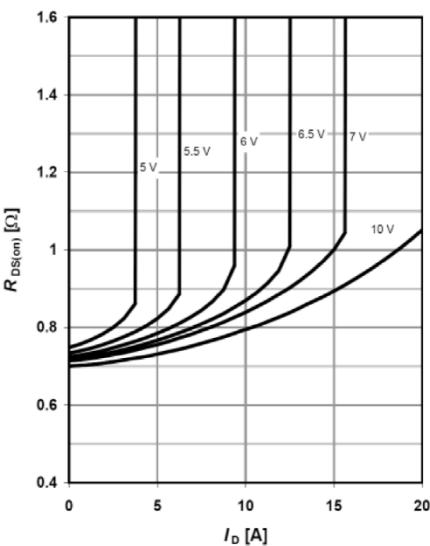
$I_D=f(V_{DS})$; $T_j=25\text{ }^\circ\text{C}$; parameter: V_{GS}

Typ. output characteristics $T_j=125\text{ }^\circ\text{C}$



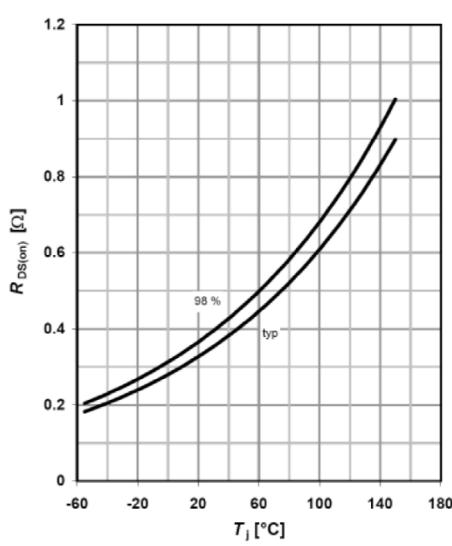
$I_D=f(V_{DS})$; $T_j=125\text{ }^\circ\text{C}$; parameter: V_{GS}

Typ. drain-source on-state resistance



$R_{DS(on)}=f(I_D)$; $T_j=125\text{ }^\circ\text{C}$; parameter: V_{GS}

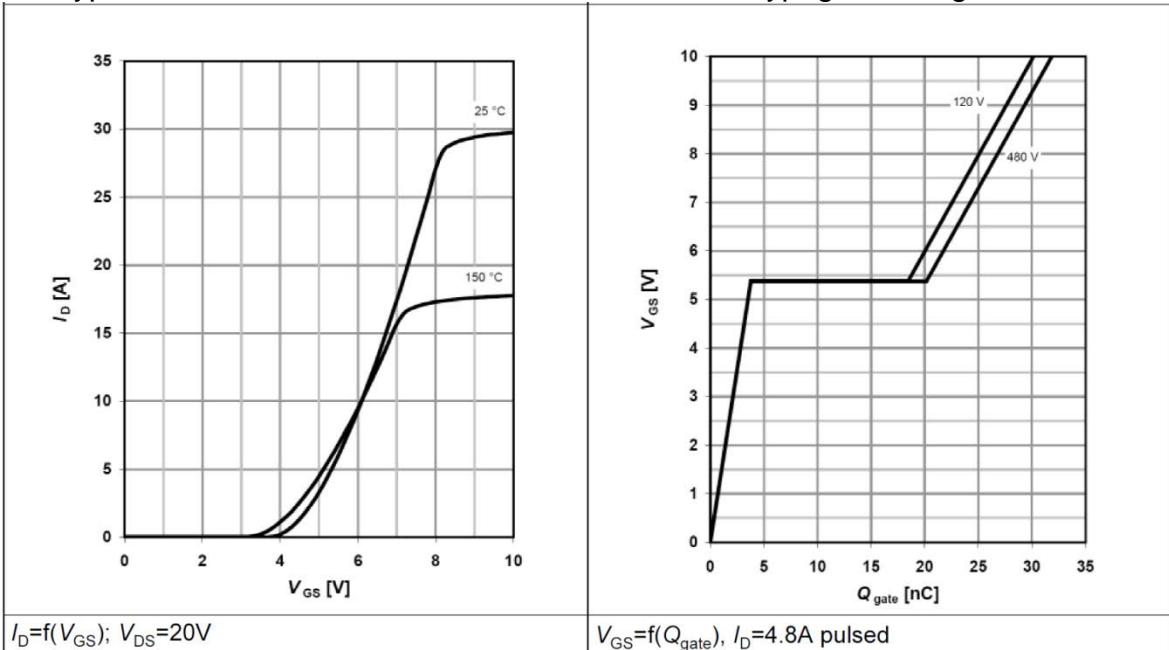
Typ. drain-source on-state resistance



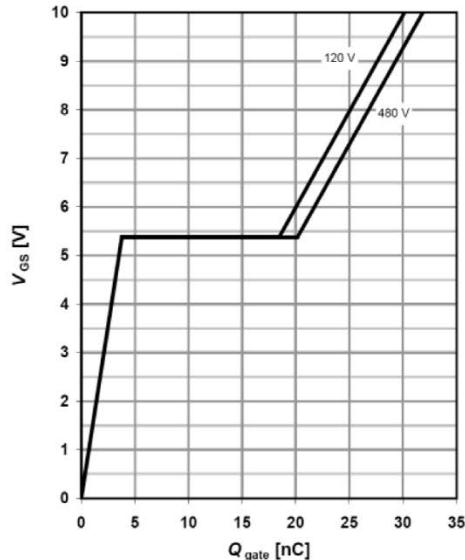
$R_{DS(on)}=f(T_j)$; $I_D=3.8\text{ A}$; $V_{GS}=10\text{ V}$

700V 11A Power MOSFET

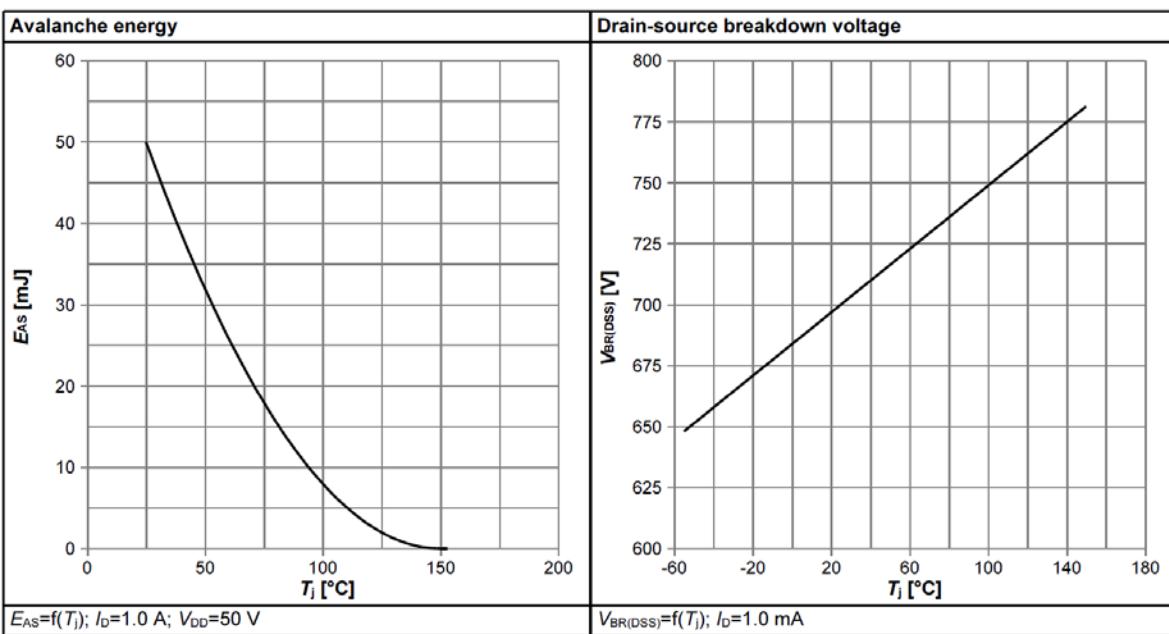
Typ. transfer characteristics



Typ. gate charge

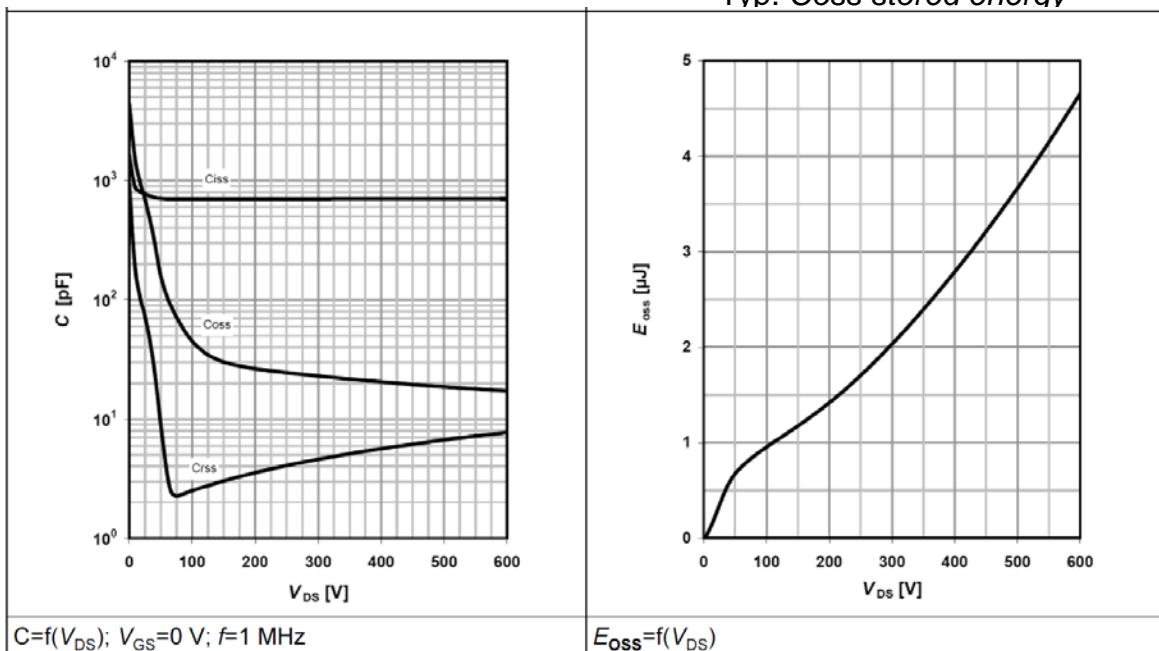


Avalanche energy

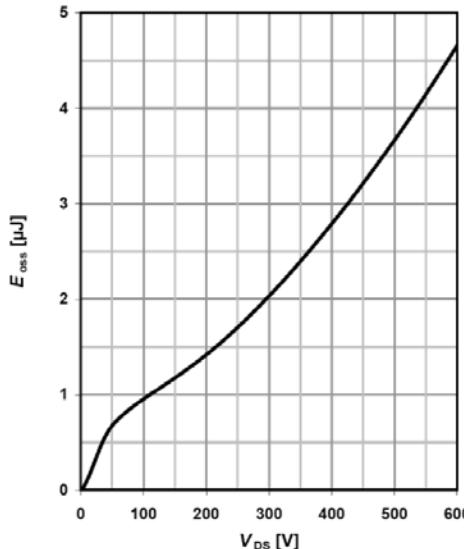


700V 11A Power MOSFET

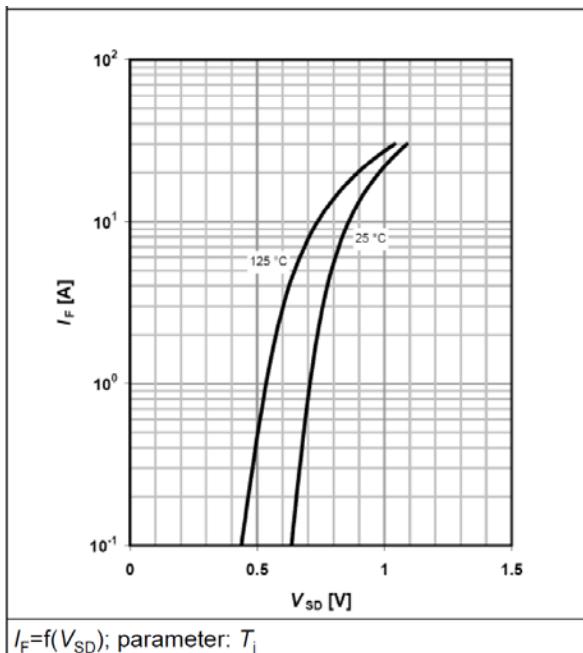
Typ. capacitances



Typ. C_{oss} stored energy



Forward characteristics of reverse diode



700V 11A Power MOSFET

Table 20 Switching times test circuit and waveform for inductive load

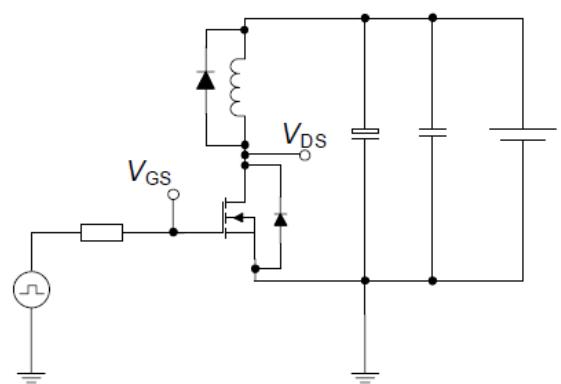
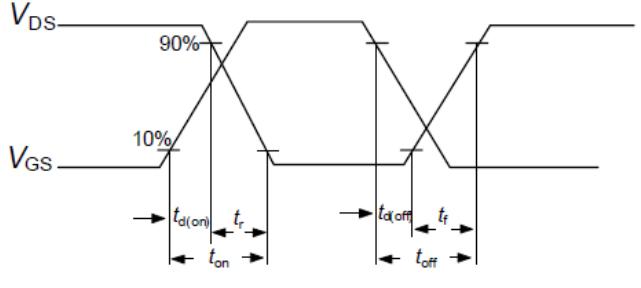
Switching times test circuit for inductive load	Switching time waveform
	

Table 21 Unclamped inductive load test circuit and waveform

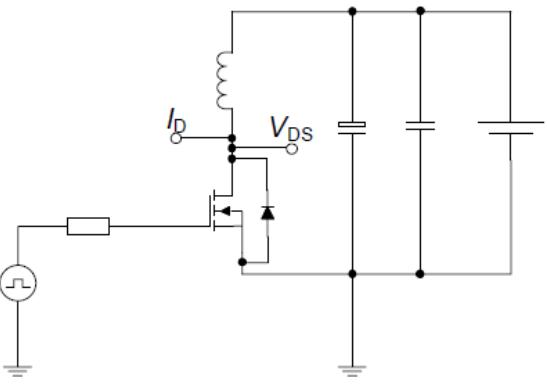
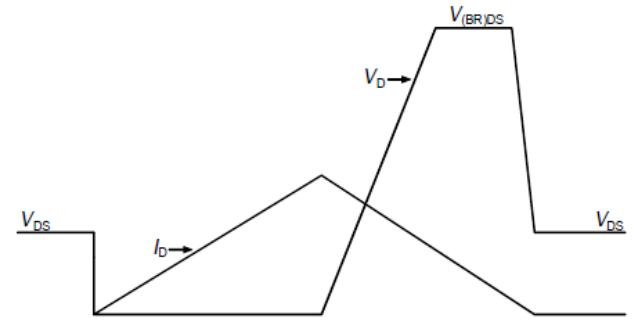
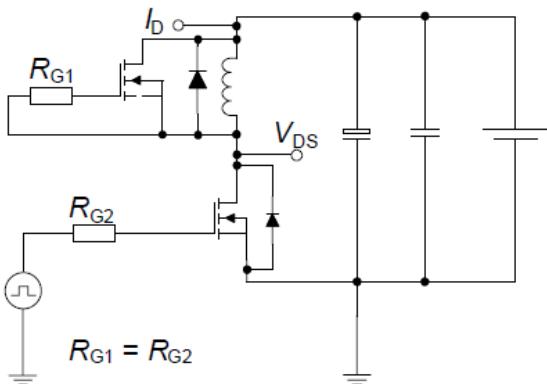
Unclamped inductive load test circuit	Unclamped inductive waveform
	

Table 22 Test circuit and waveform for diode characteristics

Test circuit for diode characteristics	Diode recovery waveform
 <p>$R_{G1} = R_{G2}$</p>	